

CLAIMS:

1. A wafer processing apparatus including a mini-environment portion having a chamber therein and used for transferring a wafer between a clean box having a lid and housing the wafer and the chamber, said apparatus comprising:

a first opening portion which is formed on a part of a wall comprising the chamber to be in communication with the chamber, facing to an opening of the clean box so as to allow loading and unloading the wafer between the clean box and the mini-environment portion; and

a door that closes, when the transfer of the wafer is not performed, the first opening portion and opens, when the transfer of the wafer is performed,

wherein when the wafer transferring operation is performed, the clean box is fixed with a first clearance having a predetermined distance between the opening formed plane of the clean box and the outside surface of the part of the wall in which the first opening portion is formed.

2. A wafer processing apparatus according to claim 1, wherein in case that the door is positioned to substantially close the first opening portion, a second clearance through which the chamber and the exterior of the mini-environment portion are in communication with each other exists.

3. A wafer processing apparatus according to claim 2, wherein the second clearance is in communication with the first clearance so as to form a gas flow path for flowing the gas from the chamber to the exterior of the mini-environment portion.